

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the present application.

Listing of Claims:

Claim 1 (currently amended): A wafer holder for semiconductor manufacturing ~~device~~ equipment, the wafer holder having a wafer-carrying surface for carrying wafers, the wafer-carrying surface having a planarity of 0.5 mm or less and comprising multiple nubs formed ~~thereon the wafer-carrying surface~~, said nubs each having a flat portion whose surface area is 70 mm^2 or less per nub, wherein the total surface area of the flat portions of said multiple nubs is 40% or less of the surface area of wafers that the wafer holder carries.

Claim 2 (canceled)

Claim 3 (currently amended): Semiconductor manufacturing ~~device~~ equipment wherein the wafer holder set forth in claim 1 is installed.

Claim 4 (canceled)

Claim 5 (currently amended): A wafer holder for semiconductor manufacturing ~~device~~ equipment, the wafer holder having a wafer-carrying surface for carrying wafers and comprising multiple nubs formed on the wafer-carrying surface and each having a flat portion, the total surface area of the flat portions of said multiple nubs being 40% or less of the surface area of wafers that the wafer holder carries, the wafer-carrying surface having a planarity of 0.5 mm or less.

Claim 6 (original): Semiconductor manufacturing device wherein the wafer holder set forth in claim 5 is installed.